

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

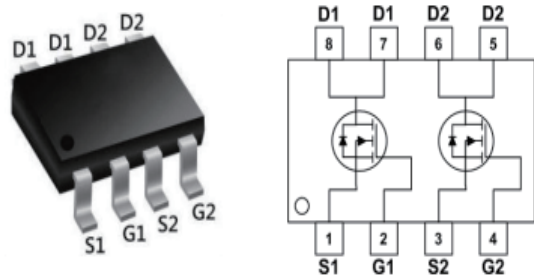
## Product Summary

BVDSS	RDS(ON)	ID
20V	20mΩ	6A

## Description

the 9926A uses advanced trench technology and design to provide excellent RDS(ON) with low gate charge. it can be used in a wide variety of applications.

## Dual SOP8 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	±12	V
$I_D@T_A=25^{\circ}C$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	6	A
$I_D@T_A=70^{\circ}C$	Continuous Drain Current, $V_{GS} @ 4.5V^1$	4.8	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	25	A
$P_D@T_A=25^{\circ}C$	Total Power Dissipation <sup>3</sup>	1.65	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	78	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	---	°C/W

**Electrical Characteristics ( $T_J = 25^\circ\text{C}$  unless otherwise specified)**

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=20V, V_{GS}=0V,$	-	-	1	$\mu A$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 12V$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.4	0.7	1	V
$R_{DS(on)}$	Static Drain-Source on-Resistance note2	$V_{GS}=4.5V, I_D=6A$	-	20	28	m $\Omega$
		$V_{GS}=2.5V, I_D=5A$	-	25.5	38	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=10V, V_{GS}=0V, f=1.0MHz$	-	358	-	pF
$C_{oss}$	Output Capacitance		-	69.3	-	
$C_{rss}$	Reverse Transfer Capacitance		-	58.5	-	
$Q_g$	Total Gate Charge	$V_{DS}=10V, I_D=3A, V_{GS}=4.5V$	-	5.6	-	nC
$Q_{gs}$	Gate-Source Charge		-	0.8	-	
$Q_{gd}$	Gate-Drain( "Miller" ) Charge		-	1	-	
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=10V,$ $I_D=6A, R_{GEN}=3\Omega, V_{GS}=4.5V$	-	16	-	ns
$t_r$	Turn-on Rise Time		-	51	-	
$t_{d(off)}$	Turn-off Delay Time		-	21	-	
$t_f$	Turn-off Fall Time		-	19	-	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current		-	-	6	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	24	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S=6A$	-	-	1.2	V

**Notes:**

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 0.5\%$

## Typical Electrical and Thermal Characteristics (Curves)

Figure 1: Output Characteristics

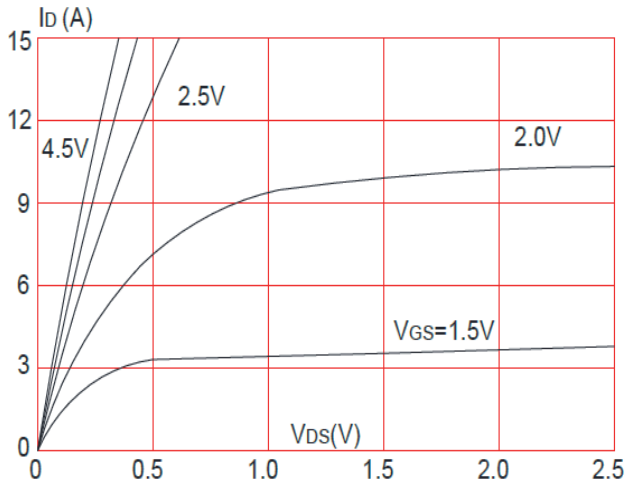


Figure 2: Typical Transfer Characteristics

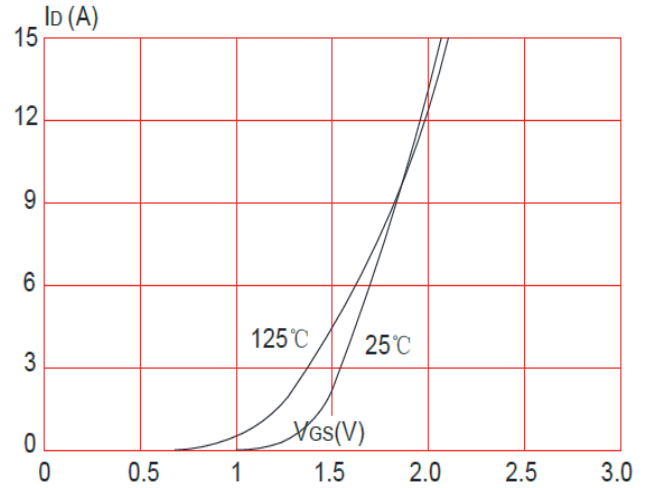


Figure 3: On-resistance vs. Drain Current

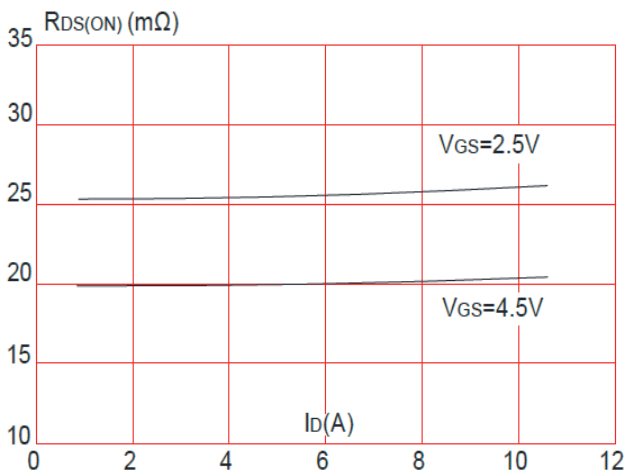


Figure 4: Body Diode Characteristics

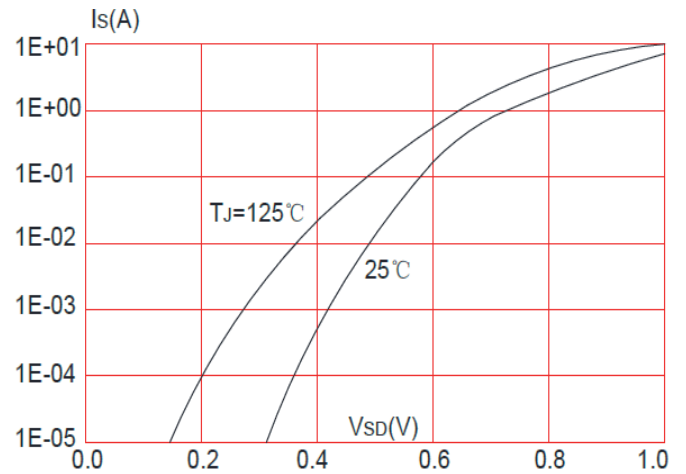


Figure 5: Gate Charge Characteristics

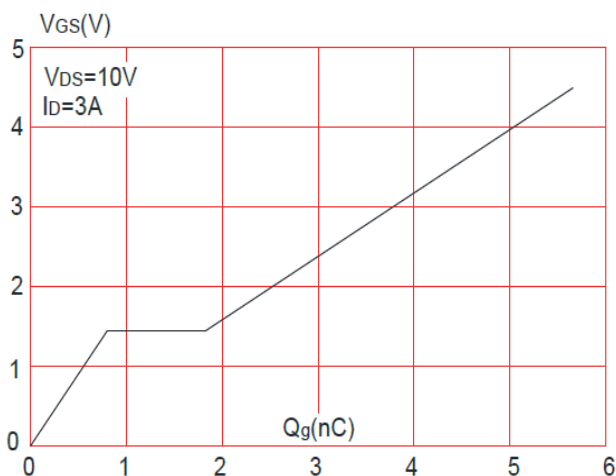
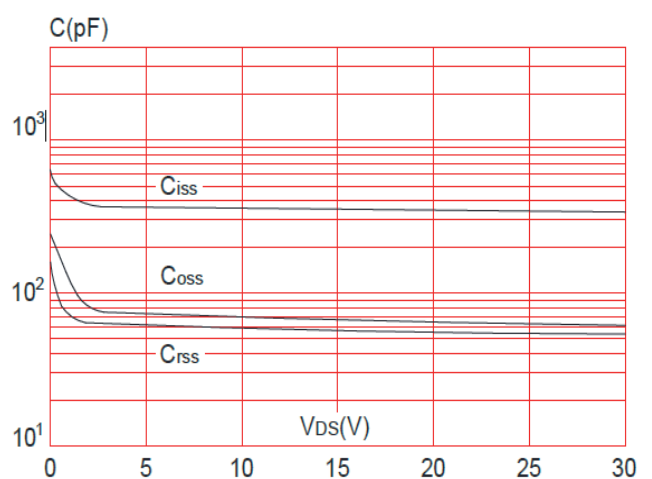


Figure 6: Capacitance Characteristics



## Typical Performance Characteristics

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

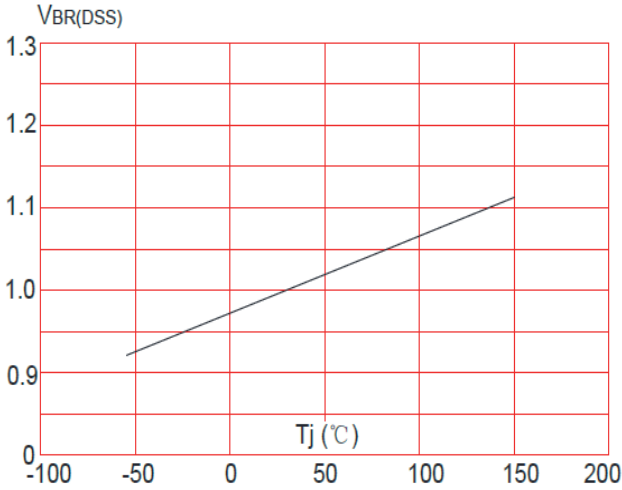


Figure 8: Normalized on Resistance vs. Junction Temperature

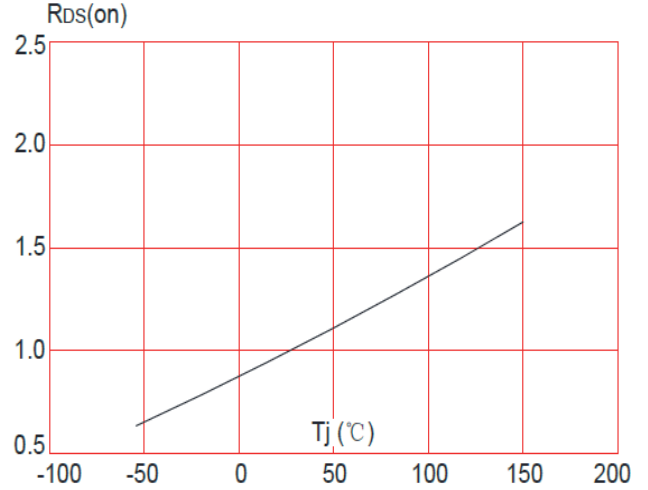


Figure 9: Maximum Safe Operating Area

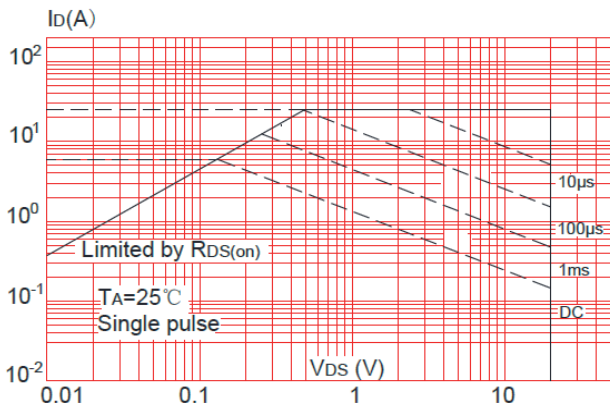


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

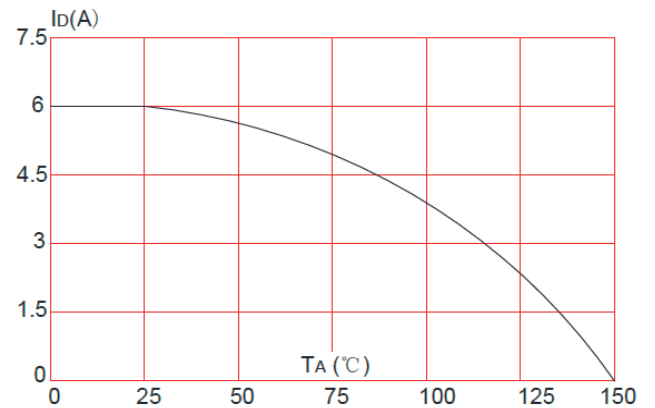
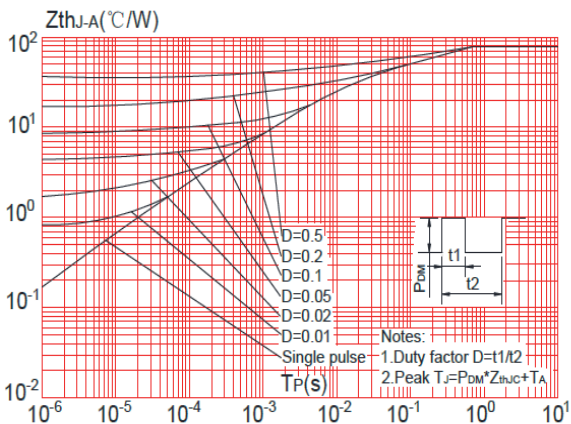
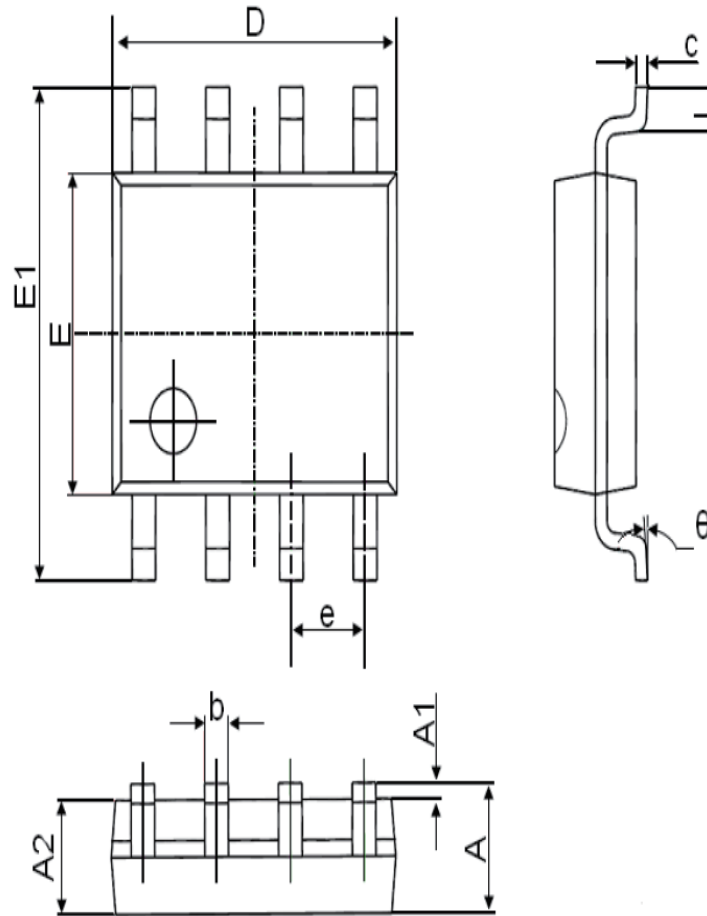


Figure 11: Maximum Effective Transient Thermal Impedance vs. Junction to Ambient Temperature



## Package Mechanical Data-SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.35	1.75	0.053	0.069
A1	0.1	0.25	0.004	0.01
A2	1.35	1.55	0.053	0.061
b	0.33	0.51	0.013	0.02
c	0.17	0.25	0.006	0.01
D	4.7	5.1	0.185	0.2
E	3.8	4	0.15	0.157
E1	5.8	6.2	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.4	1.27	0.016	0.05
θ	0°	8°	0°	8°